

ANTIMICROBIAL CONTAINING SOLVENTLESS

HOT MELT ADHESIVE COMPOSITION

Abstract of the Disclosure

5 An adhesive composition having dispersed therein a broad
spectrum antimicrobial agent for use in medical applications,
such as an adhesive for surgical drapes, wound dressings and
tapes. The adhesive is composed of acrylic polymers,
tackifiers and a preferred antimicrobial agent, diiodomethyl-
p-tolylsulfone. The adhesive composition is essentially
10 solventless and capable of application in a hot melt process
while maintaining stability at elevated temperatures in the
range of 275°F to 350°F, which not only allows hot melt
application, but allows for ethylene oxide sterilization under
heat stress.

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